IN THE CLAIMS:

Please cancel claims 1-21 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 22-42 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-21. (Canceled)

22. (New) A method of fabricating an optic protection film, which comprises the steps of:

a) selecting a substrate;

b) preparing a resin A and a resin B, the resin A having a plurality of first conductive particles and a plurality of second conductive particles, grain sizes of the plurality of first conductive particles are larger than grain sizes of the plurality of second conductive particles;

c) coating the substrate with the resin A;

d) solidifying the resin A to form a solidified resin A, the solidified resin A having a thickness larger than the grain sizes of the plurality of second conductive particles and smaller than the grain sizes of the plurality of first conductive particles;

e) coating the resin A and a predetermined portion of the plurality of first conductive particles with the resin B; and

f) solidifying the resin B to form a solidified resin B, an upper exterior of selected first conductive particles of the plurality of first conductive particles communicating with an exterior of an upper surface of the solidified resin B.

23. (New) The method according to claim 22, wherein, in the preparing step b), the grain size of the plurality of first conductive particles is 0.5μm to 7μm, and the grain size of the plurality of second conductive particles is 0.1μm to 0.5μm.

24. (New) The method according to claim 22, wherein the plurality of first conductive particles and the plurality of second conductive particles are selected from a group of conductive particles consisting of antimony tin oxide and indium-tin oxide.

25. (New) The method according to claim 22, wherein the substrate is selected from a group consisting of cellulose triacetate and polyethylene.

26. (New) The method according to claim 22, wherein the resin A including 1-Butanol, isopropanol, and acrylic resin.

27. (New) The method according to claim 22, wherein a solid content of the resin A is 5% to 25% by weight.

28. (New) The method according to claim 22, wherein each of the solidifying steps d) and f) including a hot baking step evaporating a solvent from a selected one of the resin A and the resin B, the temperature of the hot bake step is 50°C to 95°C and is performed for a period of time ranging from 0.5 min. to 5 min.

29. (New) The method according to claim 22, wherein each of the solidifying steps d) and f) including a resin polymerization step exposing a selected one of the resin A and the resin B to an ultraviolet light and forming a cross-link thereof.

30. (New) The method according to claim 22, wherein the resin B is an acrylic resin.

31. (New) The method according to claim 22, wherein the resin B includes a plurality of particles.

32. (New) The method according to claim 31, wherein the plurality of particles are made of silicon oxide.

33. (New) The method according to claim 31, wherein the plurality of particles having a grains size ranging from 0.1μm to 1.0μm.

34. (New) The method according to claim 22, wherein a solid content of the resin B is 45% to 50% by weight.

35. (New) An optic protection film comprising:

a) a substrate;

b) a first resin layer coating the substrate and having:

i) a resin A;

ii) a plurality of first conductive particles; and

iii) a plurality of second conductive particles, grain sizes of the plurality of first conductive particles are larger than grain sizes of the plurality of second conductive particles, the resin A having a thickness larger than the grain sizes of the plurality of second conductive particles and smaller than the grain sizes of the plurality of first conductive particles; and

c) a resin B coating the resin A and a predetermined portion of the plurality of first conductive particles, an upper exterior of selected first conductive particles of the plurality of first conductive particles communicating with an exterior of an upper surface of the solidified resin B.

36. (New) The optic protection film according to claim 35, wherein the substrate is selected from a group consisting of cellulose triacetate and polyethylene.

37. (New) The optic protection film according to claim 35, wherein the grain size of the plurality of first conductive particles is 0.5μm to 7μm, and the grain size of the plurality of second conductive particles is 0.1μm to 0.5μm.

38. (New) The optic protection film according to claim 35, wherein the plurality of first conductive particles and the plurality of second conductive particles are selected from a group of conductive particles consisting of antimony tin oxide and indium-tin oxide.

39. (New) The optic protection film according to claim 35, wherein the resin B includes a plurality of particles located in an upper portion thereof.

40. (New) The optic protection film according to claim 39, wherein the plurality of particles are made of silicon oxide and having a grains size ranging from 0.1μm to 1.0μm.

41. (New) The optic protection film according to claim 35, wherein the resin A including 1-Butanol, isopropanol, and acrylic resin having a solid content of the resin A is 5% to 25% by weight.

42. (New) The optic protection film according to claim 35, wherein the resin B is an acrylic resin having a solid content of the resin B is 45% to 50% by weight.